



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/ContentPage.aspx?pageid=Materials-Declaration>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sep 26, 2014 03:32 AM
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
LM358MX	LM358MX	SOIC-8 (AuBW).csv			NANTONG	0.083697	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration * 1 - Item(s) does not contain RoHS restricted substances per the definition above		Supplier Acceptance * Accepted
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
<div style="border: 1px solid black; min-height: 300px; margin-top: 5px;"> <div style="padding: 5px;"> Exemption List Version EL-2011/534/EU none </div> </div>		

Declaration Signature	
Supplier Signature	<div style="border: 1px solid black; height: 100px; position: relative;"> <div style="position: absolute; top: 10px; left: 10px; font-family: cursive; font-size: 2em; color: black;">David Lancaster</div> <div style="position: absolute; bottom: 5px; left: 10px; font-size: 0.8em;">DAVID LANCASTER - PRODUCT ECOLOGY MANAGER</div> </div>

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOIC-8 (AuBW).csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	2.78	Supplier	-	Silicon	2.78	7440-21-3	33215
Die Attach	Other Organic Materials	0.718	Supplier	-	Phenolic resin (in DA)	0.154	54208-63-8	1840
			Supplier	-	Silver	0.564	7440-22-4	6739
Encapsulation	Thermoplastics	39.401	B	Antimony/Antimony Compounds	Antimony Trioxide	0.788	1309-64-4	9415
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.394	6386-73-8	4707
			Supplier	-	Carbon Black	0.296	1333-86-4	3537
			Supplier	-	Epoxy Resin	11.426	29690-82-2	136516
			Supplier	-	Silica, vitreous	26.497	60676-86-0	316582
Lead Frame	Copper & its alloys	38.599	Supplier	-	Copper	37.531	7440-50-8	448415
			Supplier	-	Iron	0.926	7439-89-6	11064
			Supplier	-	Phosphorus	0.015	7723-14-0	179
			Supplier	-	Silver	0.077	7440-22-4	920
			Supplier	-	Zinc	0.05	7440-66-6	597
Plating	Other Nonferrous metals & alloys	2	Supplier	-	Tin	2	7440-31-5	23896
Wire Bond	Precious metals	0.199	Supplier	-	Gold	0.199	7440-57-5	2378